



## Material Declaration Data Sheet

Product: **Server System SR4850HW4M**

Manufacturer: Intel Corporation

Note: This declaration applies to all associated product codes noted on Page 2

Lead Free (Pb) Product: **NO**

Date: June 21, 2006

### Restriction on Hazardous Substances (RoHS) Compliance

#### RoHS Definition

- Quantity limit of 0.1% by mass (1000PPM) for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE)
- Quantity limit of 0.01% by mass (100 PPM) for: Cadmium

Intel understands RoHS requires: Lead and other materials banned in the RoHS Directive are either (1) below all applicable substance thresholds as proposed by the EU or (2) an approved/pending exemption applies. (Note: RoHS implementing details are not fully defined and may change.)

#### RoHS Declaration

- 1. Lead in glass of cathode ray tubes, electronic components and fluorescent tubes.
- 2. Lead as an alloying element in steel containing up to 0.35 % lead by weight.
- 3. Lead as an alloying element in aluminum containing up to 0.4 % lead by weight.
- 4. Lead as an alloying element in copper containing up to 4 % lead by weight.
- 5. Lead in high melting temperature type solders (i.e. lead based alloys containing 85 % by weight or more lead)
- 6. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
- 7. Lead in electronic ceramic parts (e.g. piezoelectronic devices).
- 8. Lead used in compliant pin connector systems.
- 9. Lead as a coating material for the thermal conduction module c-ring.
- 10. Lead in optical and filter glass.
- 11. Lead in solders consisting of more than two parts for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
- 12. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
- 13. Cadmium in optical and filter glass.
- 14. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EEC (\*) amending Directive 76/769/EEC (\*\*) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
- 15. Lead in bronze bearing shells and brushes.
- 16. Other

Where the product is declared to meet RoHS requirements, it has been verified to be in conformance with 2002/95/EC as we currently understand the requirements. Intel has systems in place to verify conformance with all applicable environmental requirements and to the best of our knowledge the information is true and correct.

INTEL ACCEPTS NO DUTY TO UPDATE THIS DECLARATION OR TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION. INTEL SHALL NOT BE LIABLE FOR ANY DAMAGES, DIRECT OR INDIRECT, CONSEQUENTIAL OR OTHERWISE, SUFFERED BY USERS OR THIRD PARTIES AS A RESULT OF THE USERS RELIANCE ON INFORMATION IN THIS DECLARATION THAT HAS BEEN UPDATED OR CHANGED.

# Product Code Information



Product Code	Description	*RoHS Exemption #
AHW4UPCISCSI	PROD CODE, PCI SCSI CABLE, 800T	,6
AHW4UPWR	PROD CODE, PS MODULE (15AMP 208)	,6
AHW4UPWR23	PROD CODE, PS MODULE (15AMP 208)	,6
AHW4URBEZEL	RACK BEZEL (BLACK) FOR SRHW4	None
AHWEXTSCSI	INTERNAL CABLE FOR EXTERNAL SCSI PORT	None
AHWIMMADV2	PROD CODE, IMM, ADV, HW, GOLD	,6
AHWIMMPRO2	PROD CODE, IMM, PRO, GOLD	,6
AHWINTSCSI	INTERNAL SCSI CBL (TO 5.25" BAY )	None
AHWPCISCSI	PROD CODE, PCI SCSI CABLE, 800T	,6
AHWPROCBLANK	INTEL CEK PROCESSOR HEATSINK	,2
AHWPROCHS	INTEL CEK PROCESSOR HEATSINK	,6
AHWVRMCM	DUAL-OUTPUT PROCESSOR VRM TULSA	None
AHWVRMPM	10.2 PROCESSOR VRM PAXVILLE MP	None
AXXBCPMOD2	PROD CODE, BUTTON CONTROL MODULE	,6
AXXCMA3U7U	RACK CABLE MANAGEMENT ARM. 3U-7U CHASSI	None
AXXLCPMOD2	PROD CODE, LCD MOD, RACK	None
AXXRAIL3U7U	RACK RAILS FOR 3U-7U CHASSIS. J-HOOK DE	None
AXXRAKU42E	INTELR RAID ACTIVATION KEY	,6
BHW4DIMMM	PROD CODE, MEMORY BOARD	,6
BHWBASEGPM05	PROD CODE, BASEBOARD - GENERAL PURPOSE	,6
BHWBASEIOM05	PROD CODE, BASEBOARD - IO PERFORMANCE	,6
BHWBASEM	PROD CODE, BASEBOARD - IO PER, H800T	,6
FHW4UCPSCSI	CNTL PNL TO SCSI BP FOR SR4850HW4. (50P)	None
FHW4UFAN	PROD CODE, SYSTEM FAN FOR THE SR4850HW4	,6
FHW4UFPSATA	FRNT PNL AND SATA BUNDLE FOR SR4850HW4	,6
FHW4UFPSCSI	FRNT PNL TO SCSI BP FOR SR4850HW4. (34P)	,6
FHW4UFRTPNL	PROD CODE, FRONT IO PANEL BOARD FOR 4U	,6
FHW4UINTSCSIA	PROD CODE, INT SCSI CABLE FOR SCSI 4U	,6
FHW4UPBAYSCSI	PWR, PBAY TO SCSI BP FOR SR4850HW4. (4U)	,6
FHW4UPCILATCH	PCI CARD HOLD DOWN LATCHES (8)	,6
FHW4UPDB	PROD CODE, POWER DISTRIBUTION BOARD, 4U	,6
FHW4UPRODUCT	PROCESSOR AIR DUCT	,6
FHW4USCSIBP	PROD CODE, SCSI BACKPLANE FOR 4U	,6
FHWINTRU	INTRUSION SWITCH SR4850HW4 SR6850HW4	,6
FHWPCIDIVIDER	PCI DIVIDERS	,6
FHWSATAIDE	SATA TO IDE BRIDGE	,6
AXXRSBBU3	PROD CODE, AXXRSBBU3, BATTERY	None

\* RoHS Exemption # corresponds with exemption #'s found on page 1.